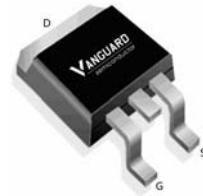


Features

- P-Channel, -5V Logic level Control
- Enhancement mode
- Very low on-resistance $R_{DS(on)}$ @ $V_{GS}=-4.5$ V
- Fast Switching
- 100% Avalanche Tested
- Pb-free lead plating; RoHS compliant

V_{DS}	-100	V
$R_{DS(on),TYP}@ V_{GS}=-10$ V	26	mΩ
$R_{DS(on),TYP}@ V_{GS}=-4.5$ V	29	mΩ
I_D	-55	A

TO-252



Drain Pin2



Source Pin3



Halogen-Free

Part ID	Package Type	Marking	Tape and reel information
VSD030P10MS	TO-252	030P10M	2500pcs/Reel

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit	
Common Ratings (T_c=25°C Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	±20	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-100	V	
T_J	Maximum Junction Temperature	175	°C	
T_{STG}	Storage Temperature Range	-55 to 175	°C	
I_S	Diode Continuous Forward Current	$T_c=25^\circ\text{C}$	-55	A
Mounted on Large Heat Sink				
I_{DM}	Pulse Drain Current Tested ①	$T_c=25^\circ\text{C}$	-180	A
I_D	Continuous Drain current@ $V_{GS}=10$ V	$T_c=25^\circ\text{C}$	-55	A
		$T_c=100^\circ\text{C}$	-35	A
P_D	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	150	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.0	°C/W	
$R_{\theta JA}$	Thermal Resistance Junction-Ambient($t_s < 10$ s)	40	°C/W	
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed ②	56	mJ	

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-100	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=-100\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=-100\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-10	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.6	-2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-25\text{A}$	--	26	30	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-10\text{A}$	--	29	35	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	7270	--	pF
C_{oss}	Output Capacitance		--	315	--	pF
C_{rss}	Reverse Transfer Capacitance		--	205	--	pF
Q_g	Gate Resistance	$f=1\text{MHz}$		13.5		Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=-50\text{V}, I_{\text{D}}=-20\text{A}, V_{\text{GS}}=-4.5\text{V}$	--	83	--	nC
Q_{gs}	Gate-Source Charge		--	15	--	nC
Q_{qd}	Gate-Drain Charge		--	36	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-50\text{V}, I_{\text{D}}=-20\text{A}, R_{\text{G}}=6.8\Omega, V_{\text{GS}}=-10\text{V}$	--	18	--	nS
t_r	Turn-on Rise Time		--	60	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	160	--	nS
t_f	Turn-Off Fall Time		--	105	--	nS
Source- Drain Diode Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
I_{SD}	Source-drain current(Body Diode)	$T_c=25^\circ\text{C}$	--	--	-55	A
V_{SD}	Forward on voltage	$I_{\text{SD}}=-25\text{A}, V_{\text{GS}}=0\text{V}$	--	0.86	-1.3	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_{\text{sd}}=-10\text{A}, V_{\text{GS}}=0\text{V}$ $dI/dt=-100\text{A}/\mu\text{s}$	--	65	--	nS
Q_{rr}	Reverse Recovery Charge			125		nC

NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

② Limited by $T_{J\text{max}}$, starting $T_J = 25^\circ\text{C}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$, $I_{\text{AS}} = -15\text{A}$, $V_{\text{GS}} = -10\text{V}$. Part not recommended for use above this value

③ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

Typical Characteristics

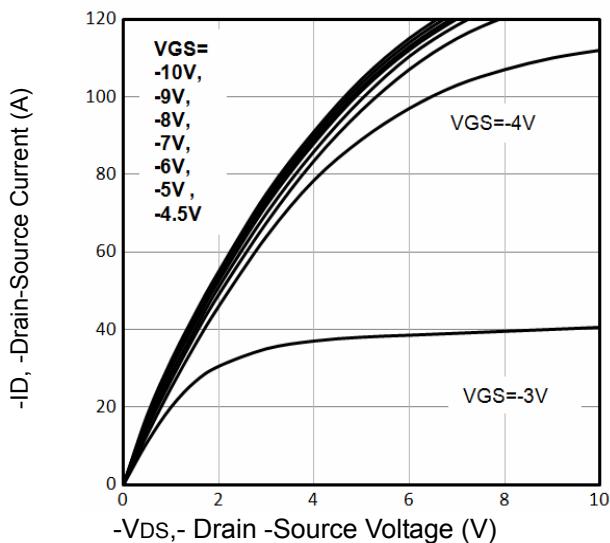


Fig1. Typical Output Characteristics

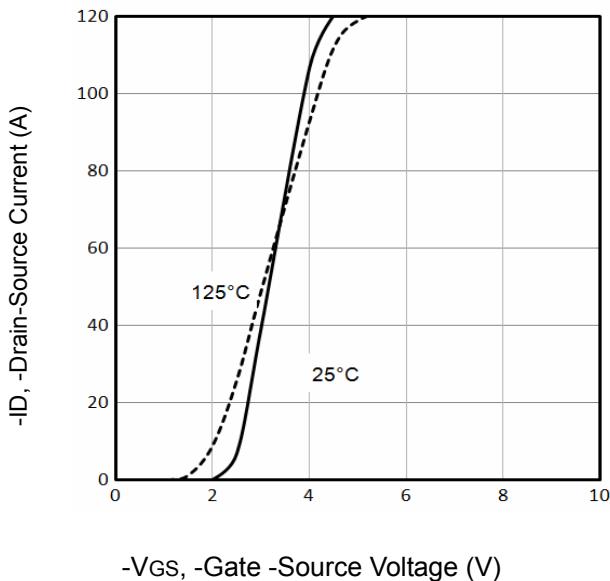


Fig3. Typical Transfer Characteristics

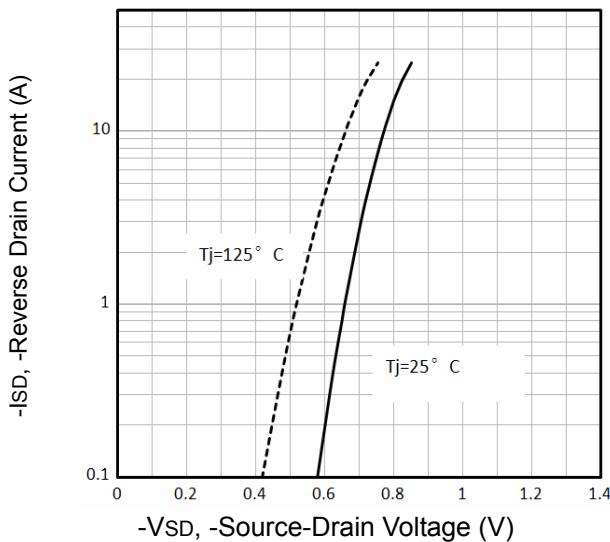


Fig5. Typical Source-Drain Diode Forward Voltage

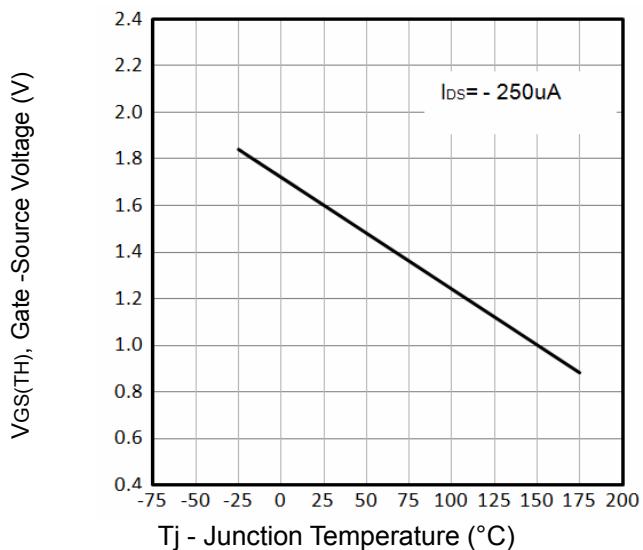


Fig2. Threshold Voltage Vs. Temperature

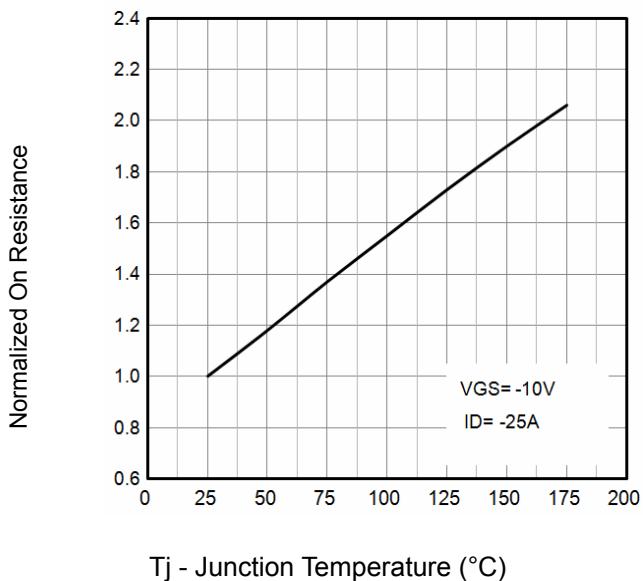


Fig4. Normalized On-Resistance Vs. Temperature

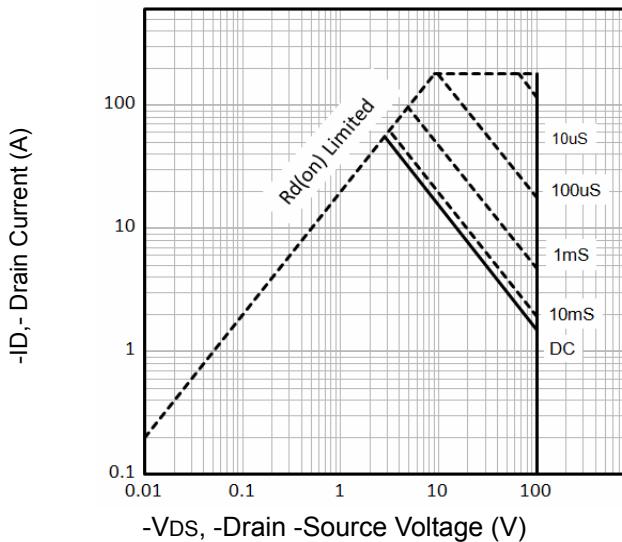


Fig6. Maximum Safe Operating Area

Typical Characteristics

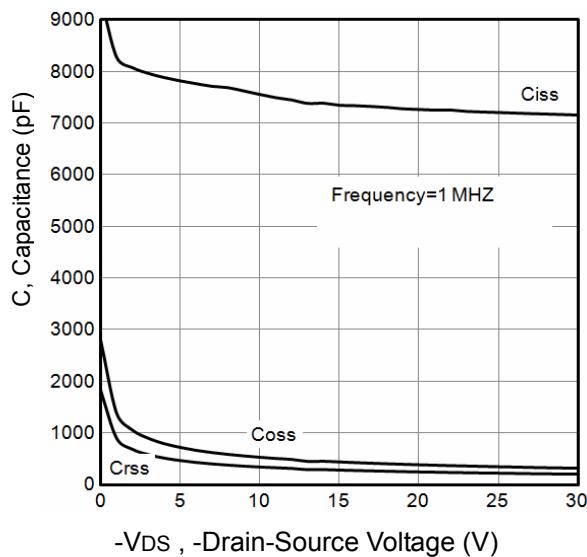


Fig7. Typical Capacitance Vs.Drain-Source Voltage

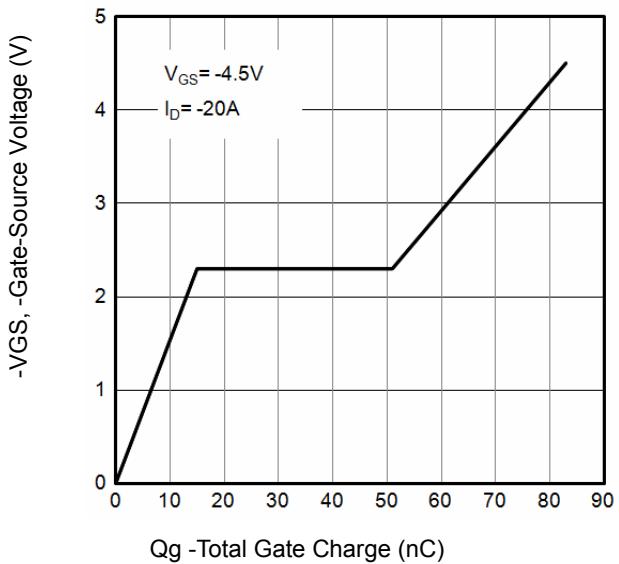


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

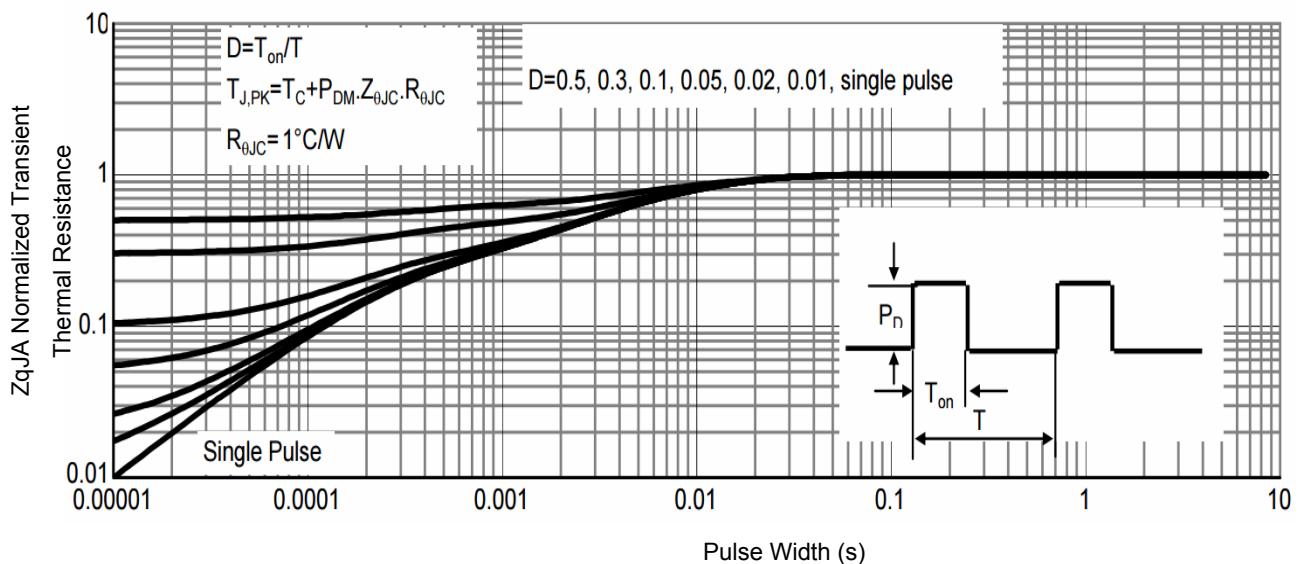


Fig9. Normalized Maximum Transient Thermal Impedance

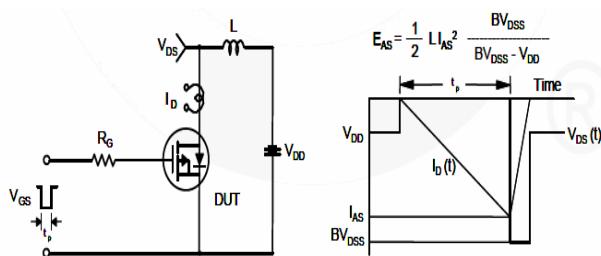


Fig10. Unclamped Inductive Test Circuit and Waveforms

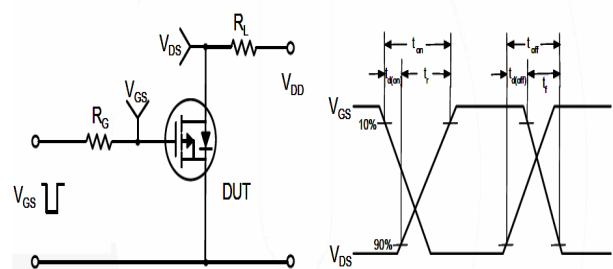
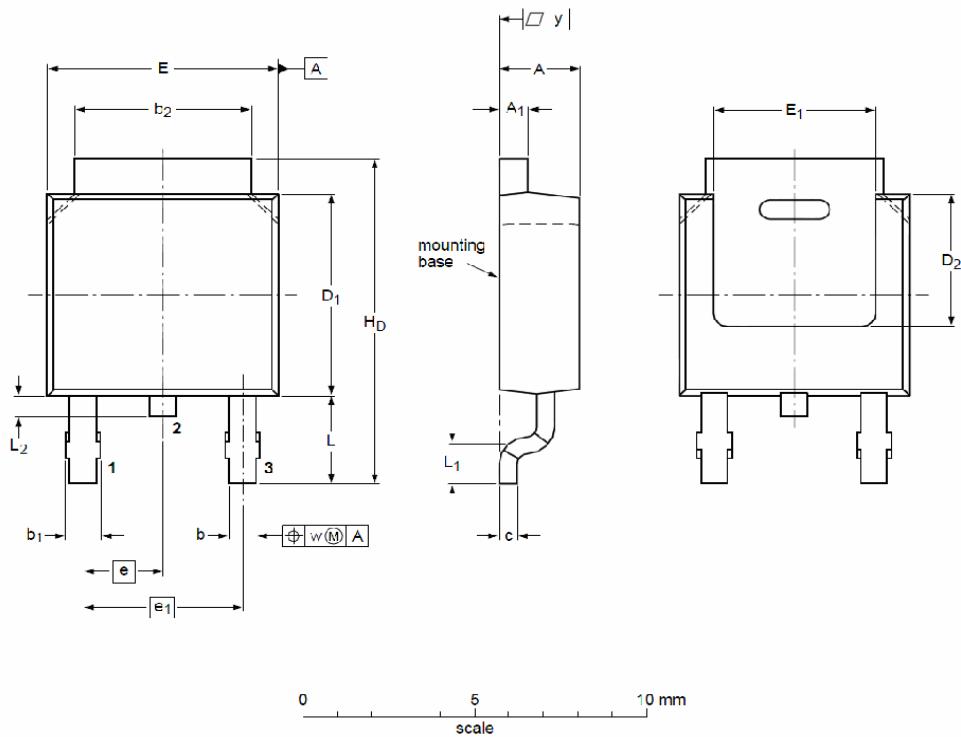


Fig11. Switching Time Test Circuit and waveforms

TO-252 Package Outline



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.22	2.30	2.38	A ₁	0.46	0.58	0.93
b	0.71	0.79	0.89	b ₁	0.90	0.98	1.10
b ₂	5.00	5.30	5.46	c	0.20	0.40	0.56
D ₁	5.98	6.05	6.22	D ₂	--	4.00	--
E	6.47	6.60	6.73	E ₁	5.10	5.28	5.45
e	--	2.28	--	e ₁	--	4.57	--
H _D	9.60	10.08	10.40	L	2.75	2.95	3.05
L ₁	--	0.50	--	L ₂	0.80	0.90	1.10
w	--	0.20	--	y	0.20	--	--

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